

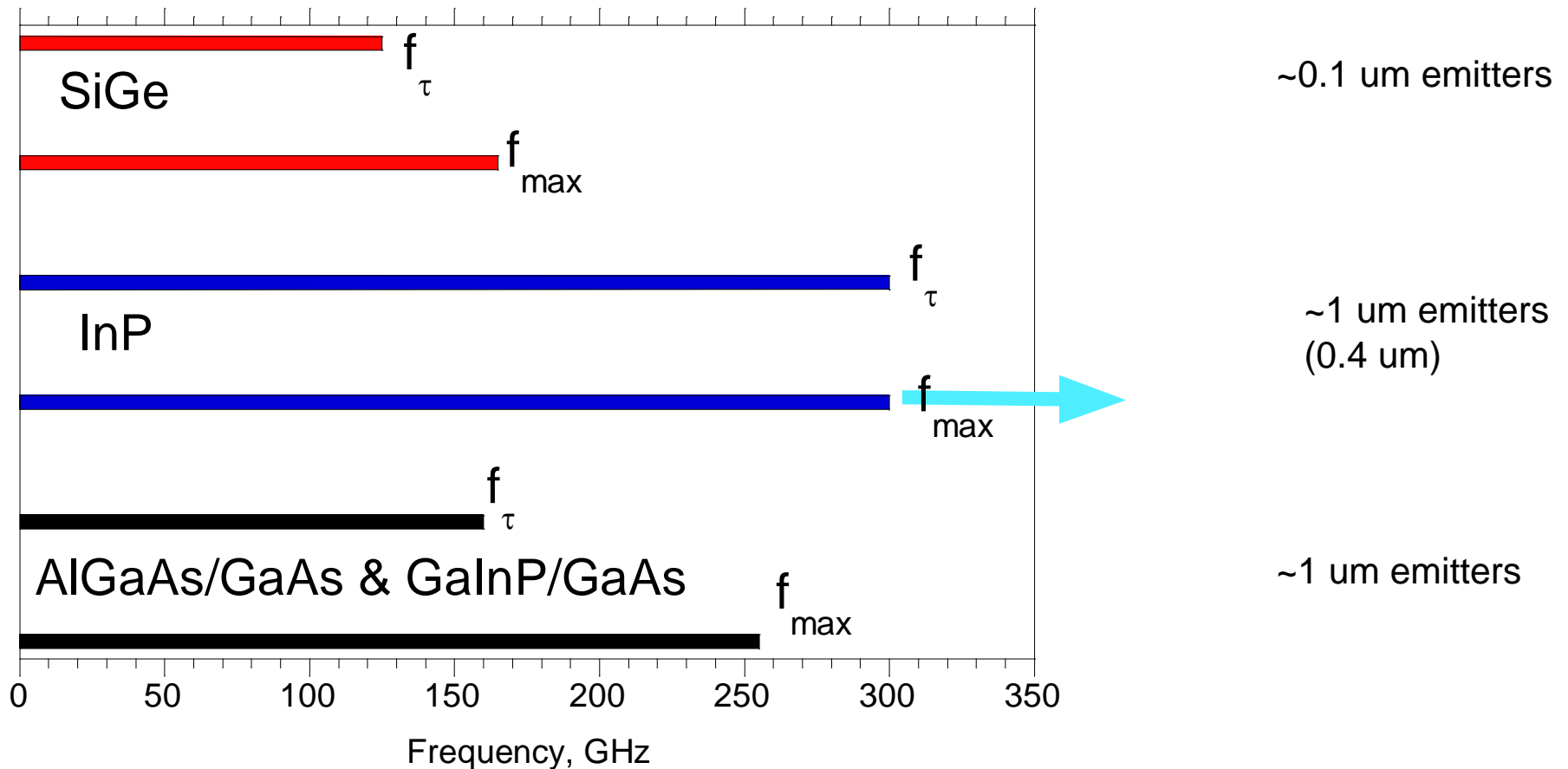
Submicron Scaling of III-V HBTs for 40-200 GHz Analog & Digital ICs

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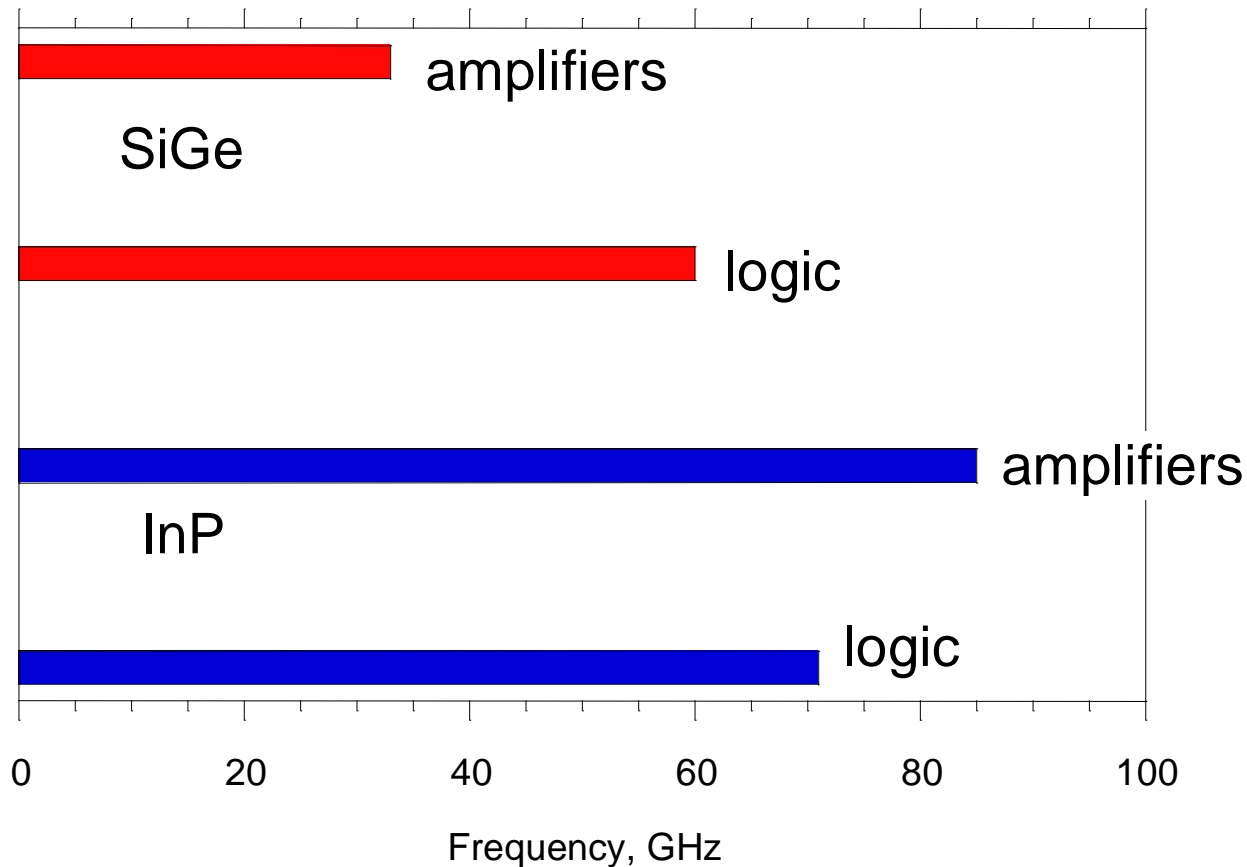
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State-of-art in HBTs, 2000: cutoff frequencies



Si / SiGe have significantly poorer material parameters
...but are ***much better scaled in size and current density***

State-of-Art in HBTs, 2000: small-scale circuits

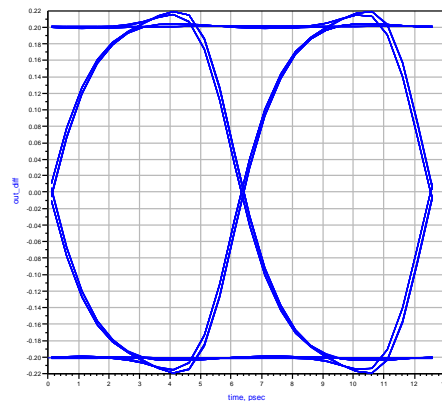
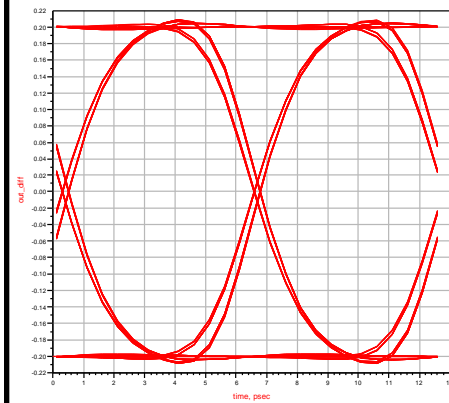
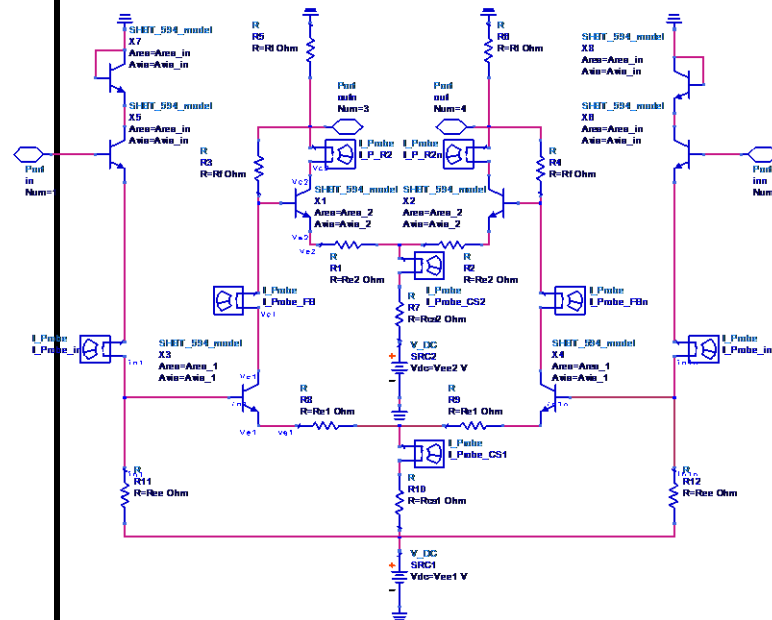
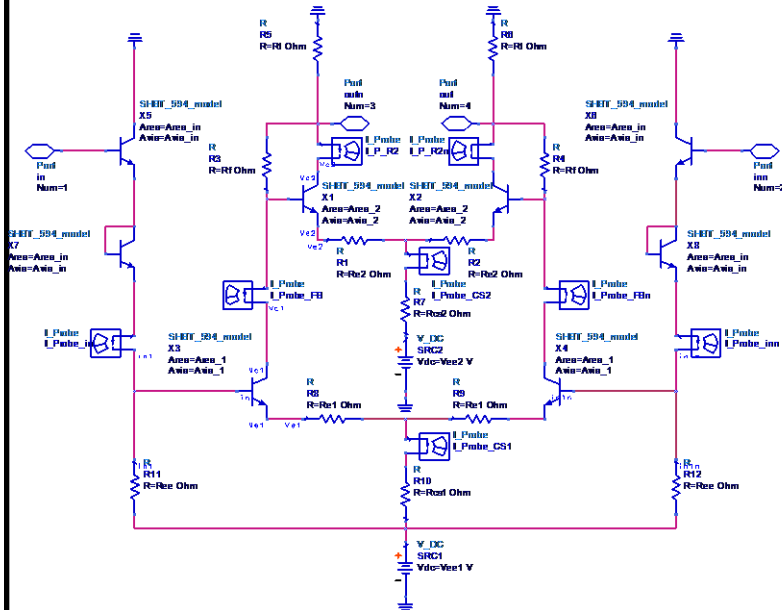


Si / SiGe has rough parity in logic with InP despite lower f_t , f_{max}

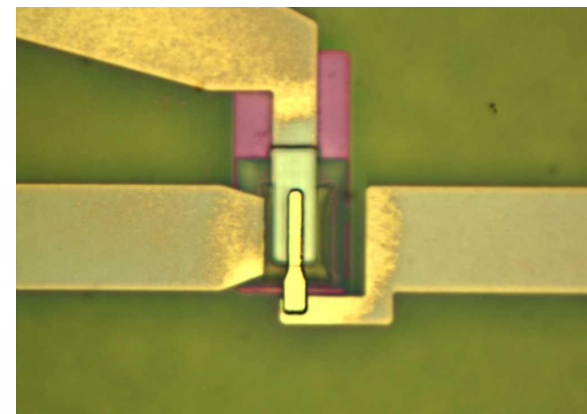
due to higher current density, better emitter contacts

Si/SiGe has significantly slower amplifiers due to lower f_t , f_{max}

Si/SiGe has ***much better scales of integration, etc***



160 Gb/s LIA simulations using UCSB HBT model



Scaling Laws for fast HBTs

for x 2 improvement of **all** parasitics:
 f_t , f_{max} , logic speed...
 base $\sqrt{2}$: 1 thinner
 collector 2:1 thinner
 emitter, collector junctions 4:1 narrower
 current density 4:1 higher
 emitter Ohmic 4:1 less resistive

Challenges with Scaling:

Collector

mesa HBT: collector under base Ohmics.
 Base Ohmics must be one transfer length
 sets minimum size for collector

Emitter Ohmic:

hard to improve...how ?

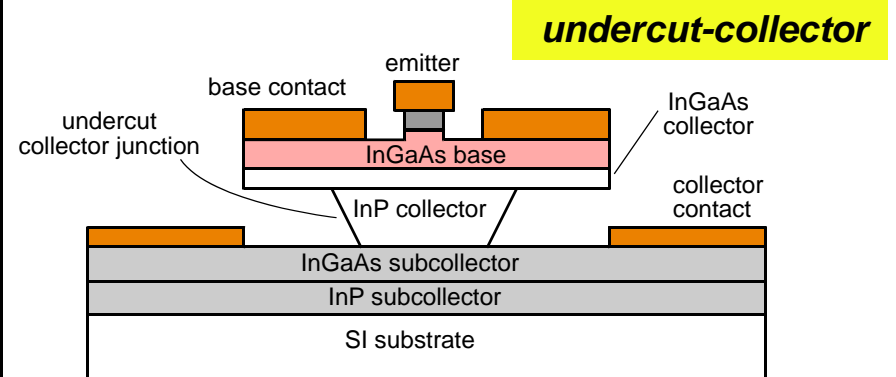
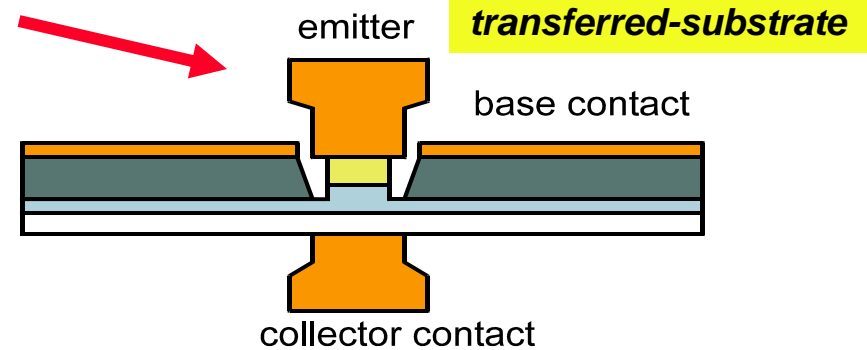
Current Density:

dissipation, reliability

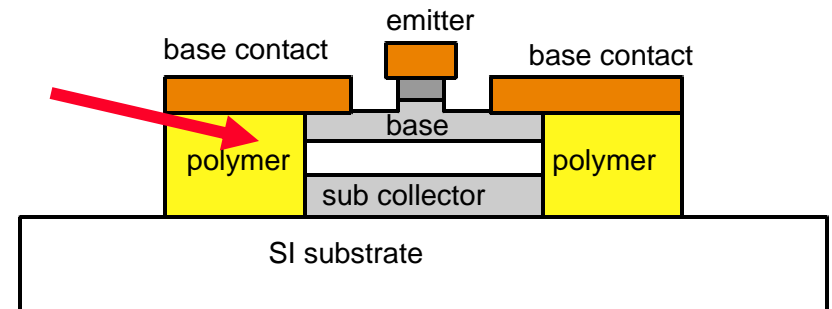
Loss of breakdown

avalanche V_{br} never less than collector E_{gap}
 (1.12 V for Si, 1.4 V for InP)

....sufficient for logic, insufficient for power



Narrow-mesa with $1E20$ carbon-doped base



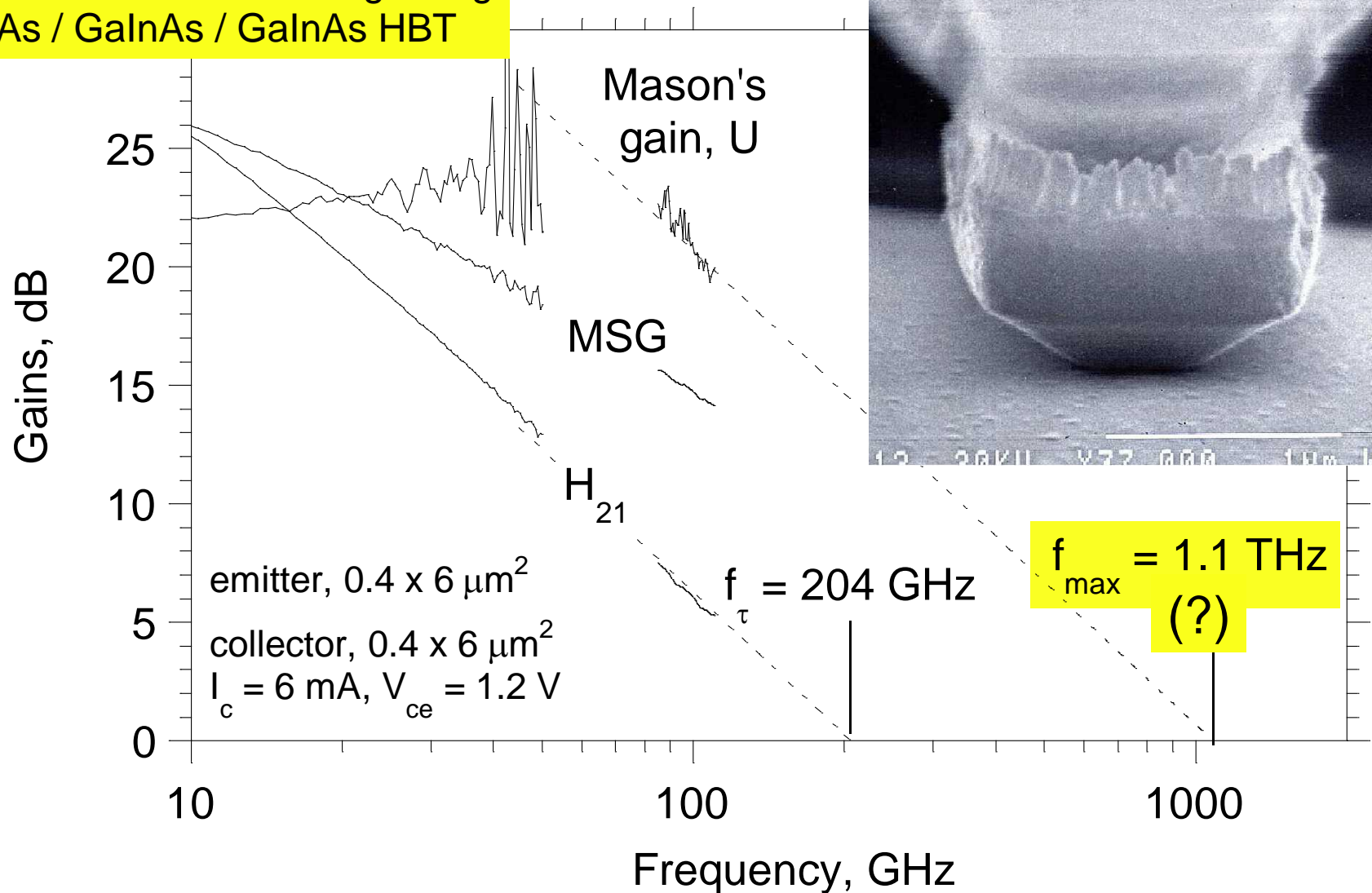


Submicron Transferred-Substrate HBT

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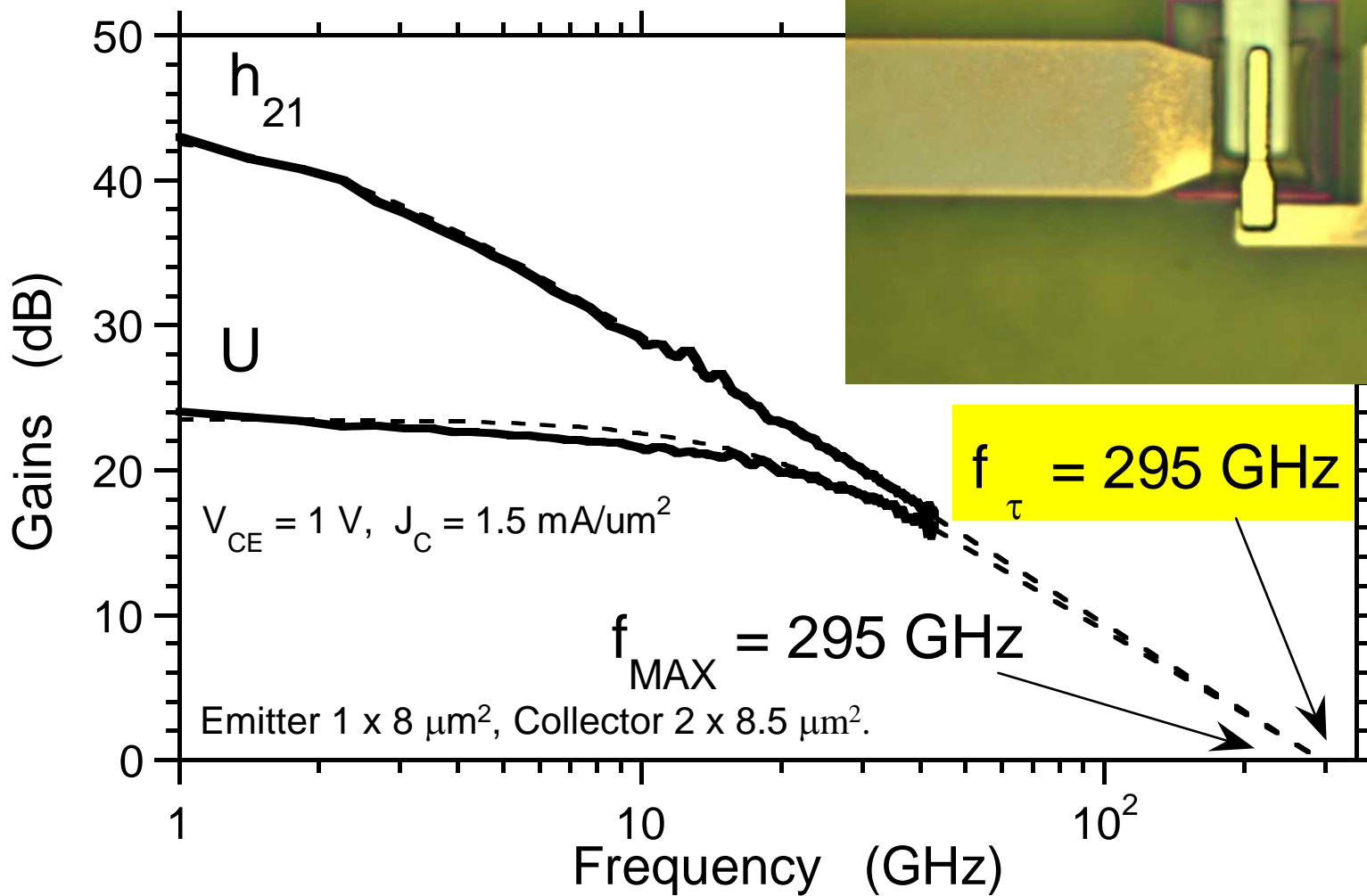
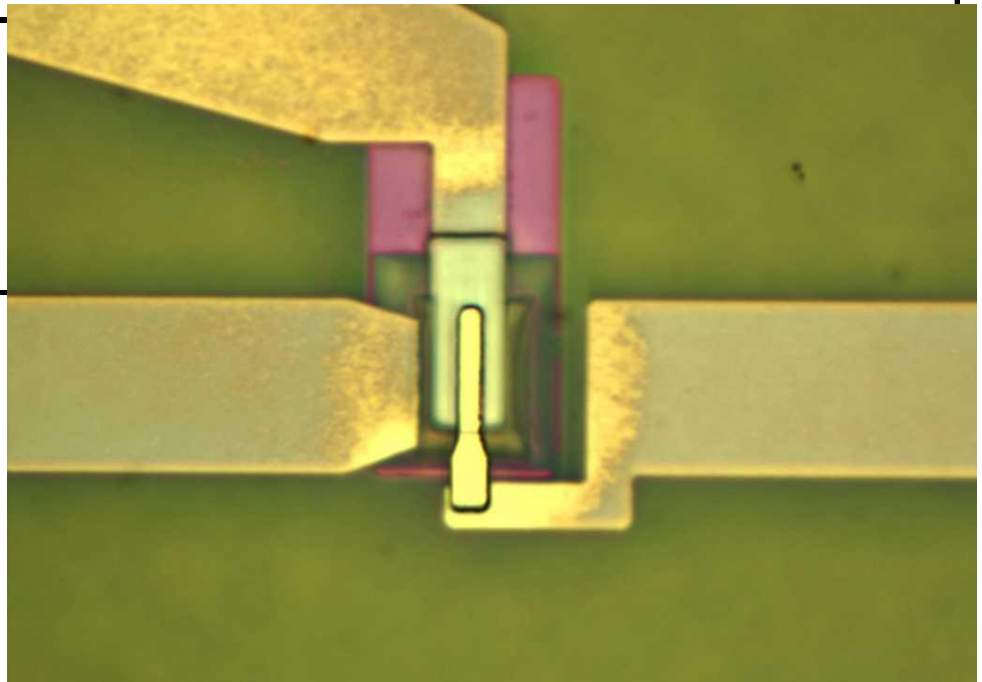
Michelle Lee

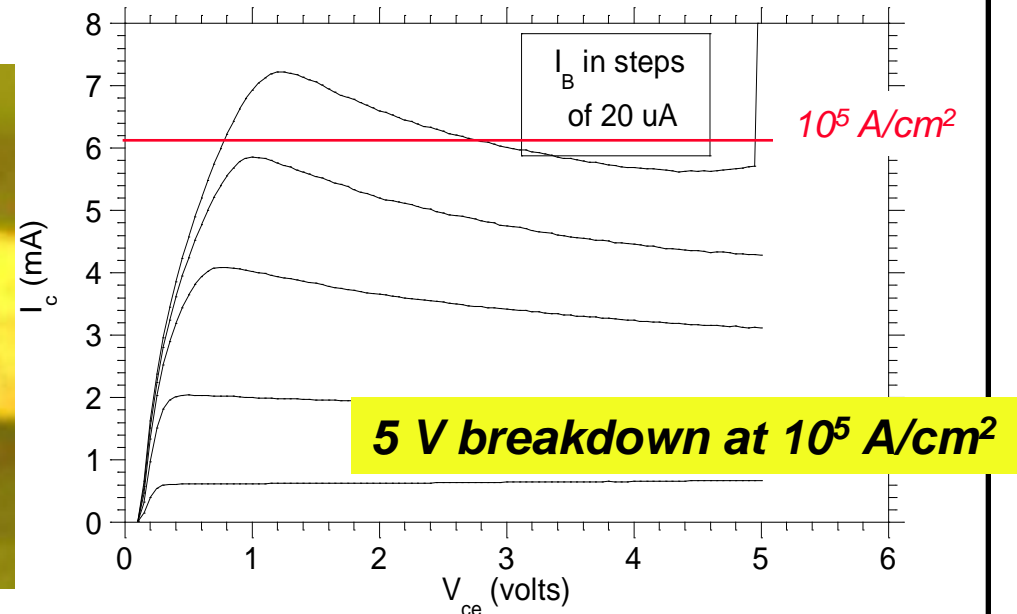
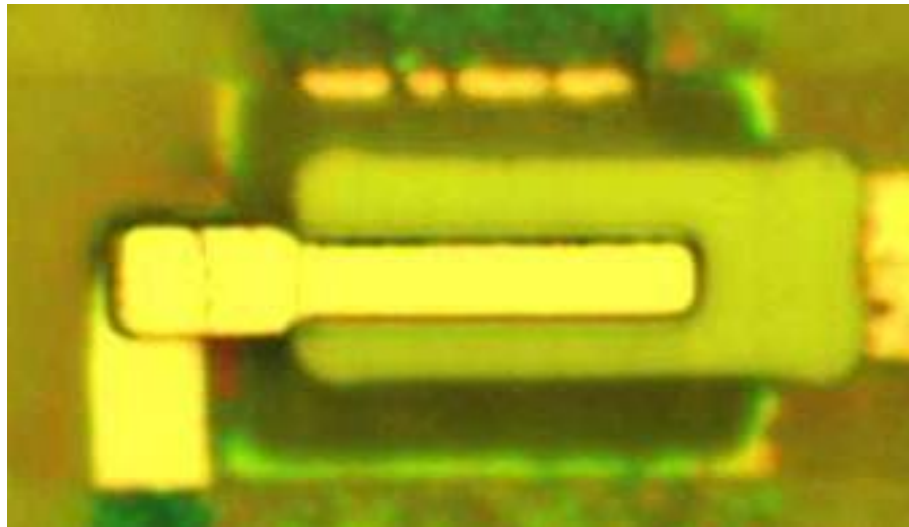
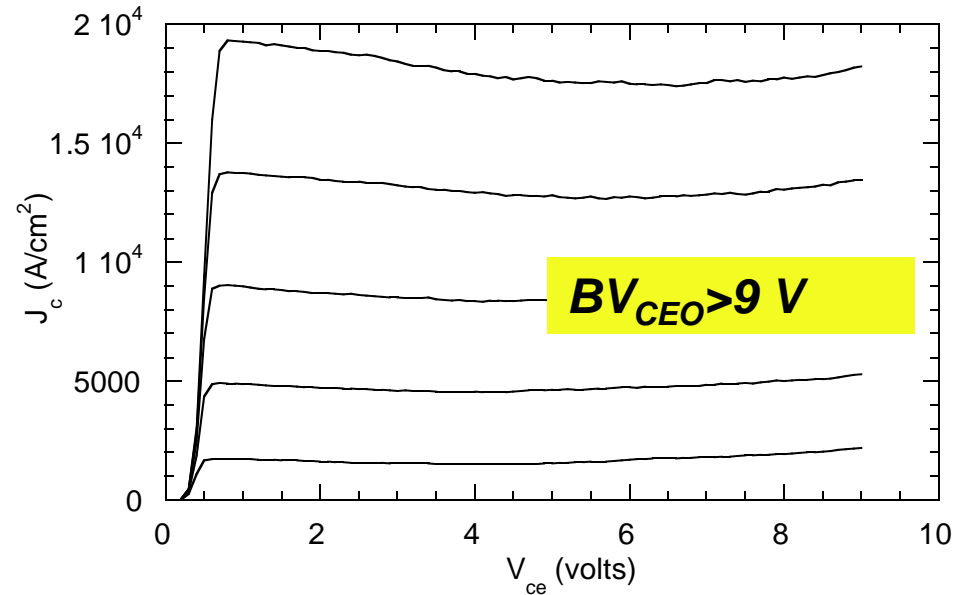
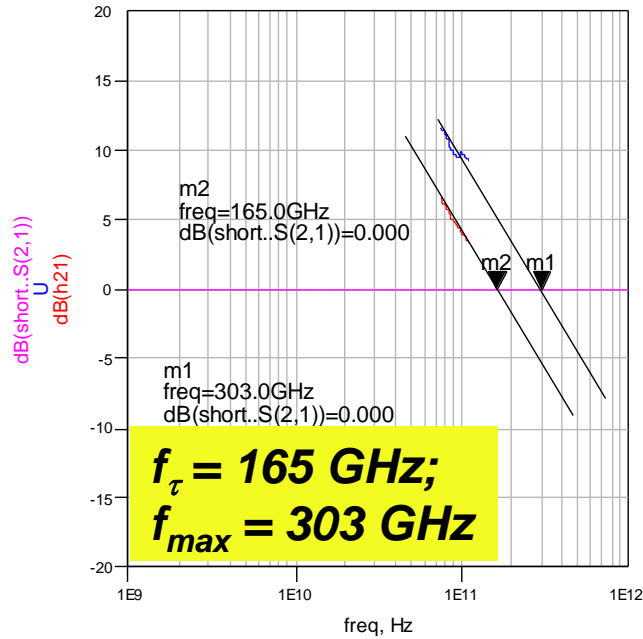
3000 Å collector
400 Å base with 52 meV grading
AllnAs / GalnAs / GalnAs HBT

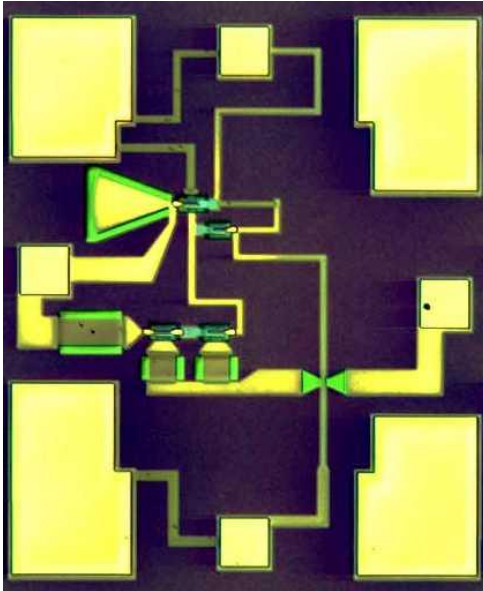


Record f_{τ} HBT

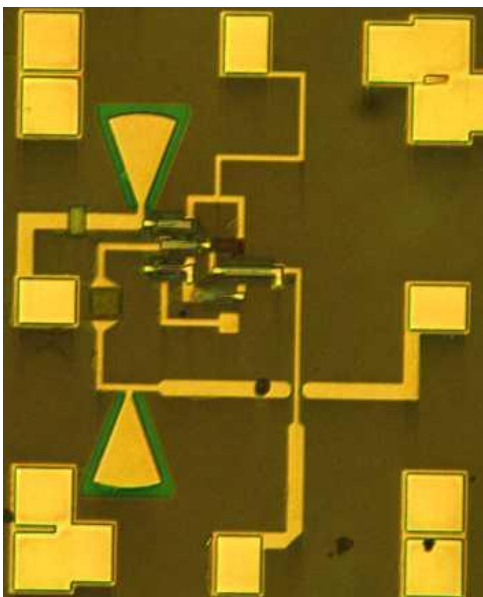
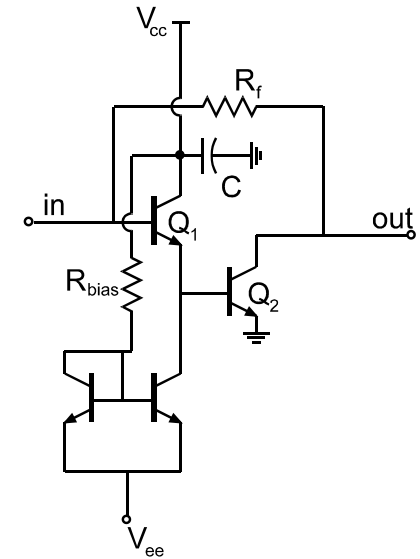
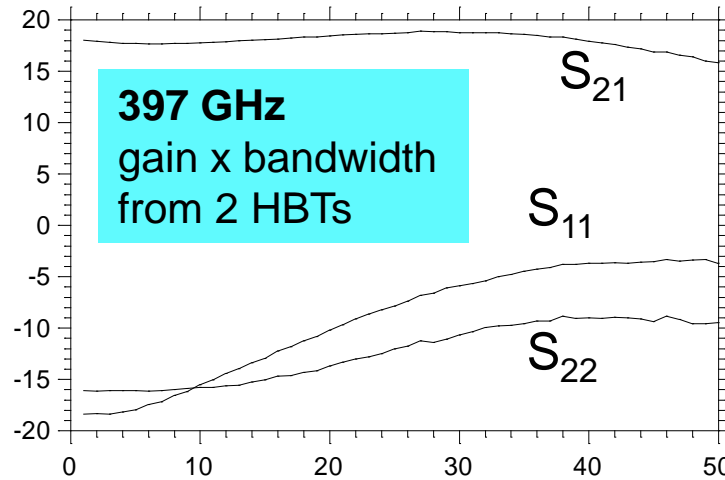
2000 Å collector
 300 Å base with 52 meV grading
 AlInAs / GaInAs / GaInAs HBT



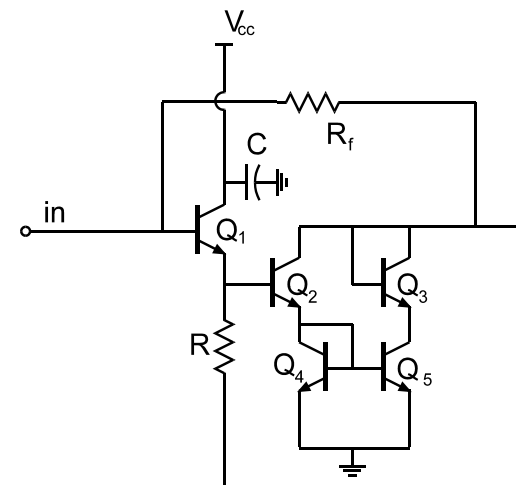
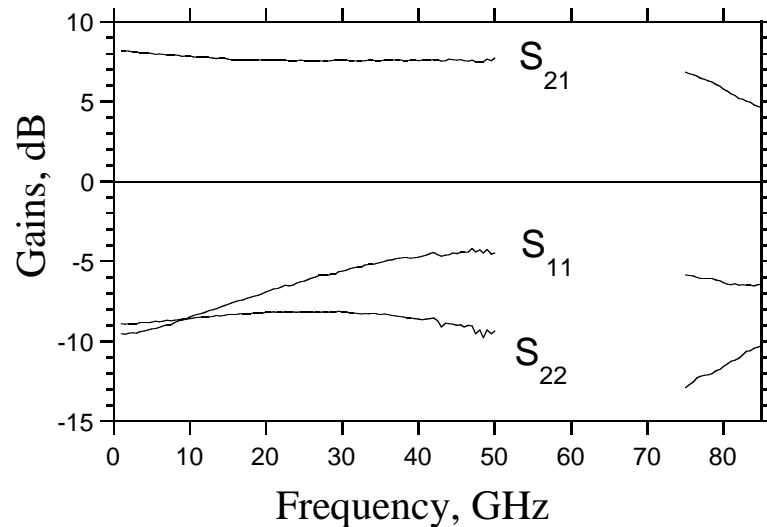




18 dB, DC-50 GHz



8.2 dB, DC-80 GHz



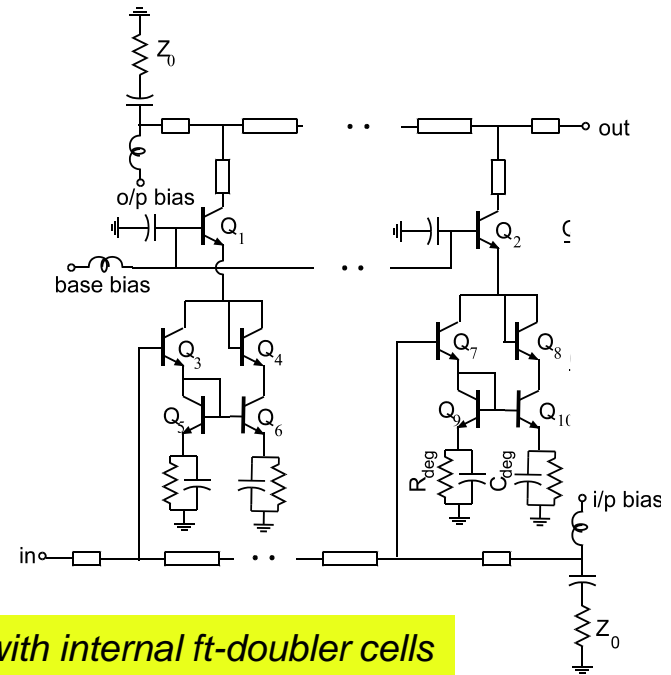
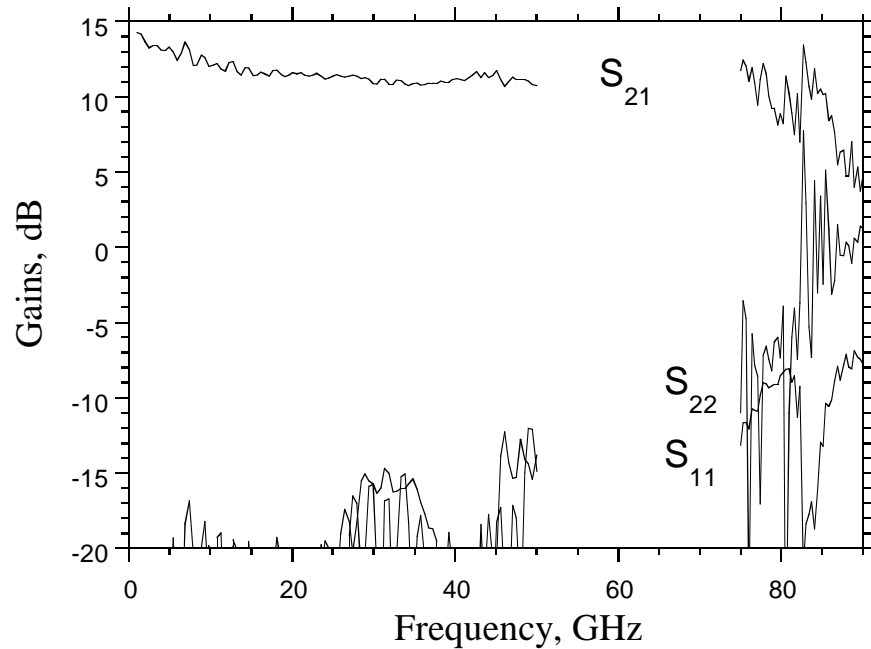
AFOSR

HBT distributed amplifier

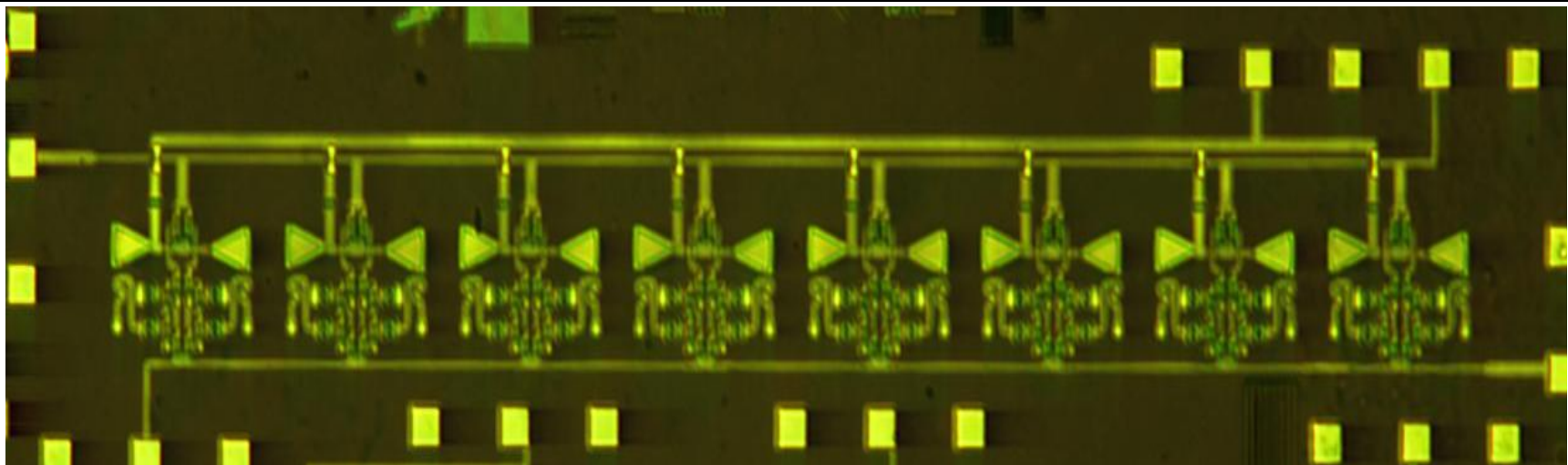
11 dB, DC-87 GHz

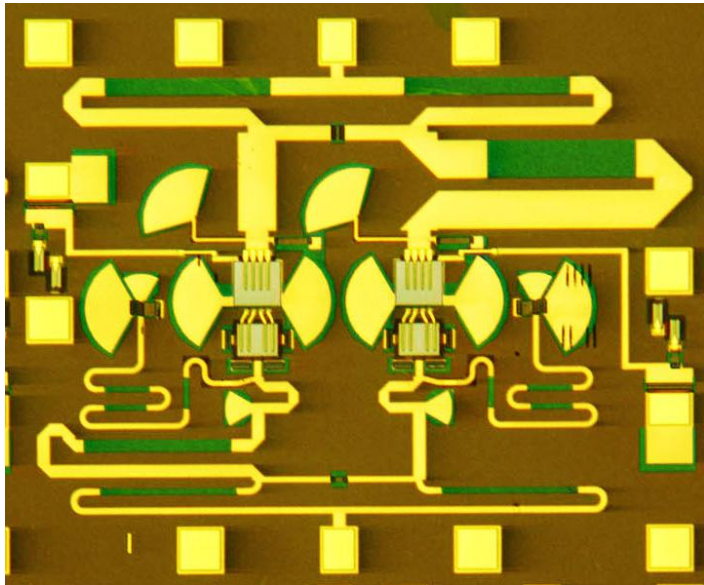
UCSB

PK Sundararajan

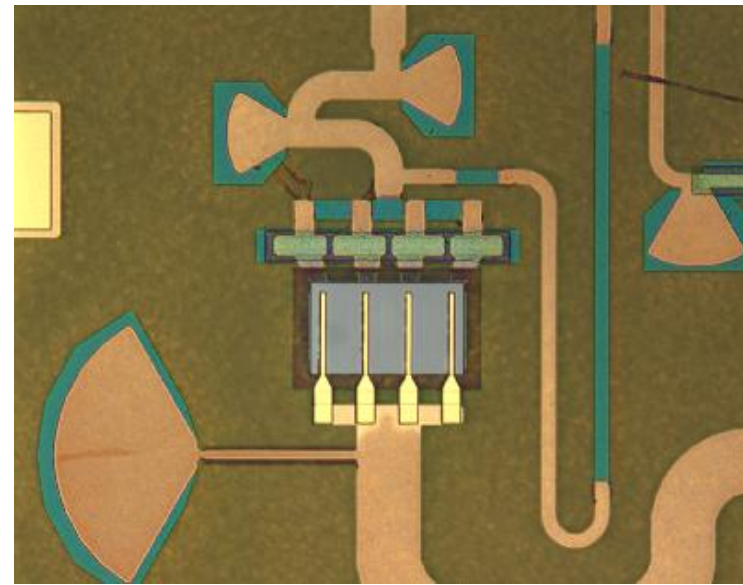


TWA with internal ft-doubler cells





Balanced Amplifier: 10.7dBm at 78GHz



Common-Base Amplifier: 9.7dBm at 82.5 GHz

(transferred-substrate HBT)

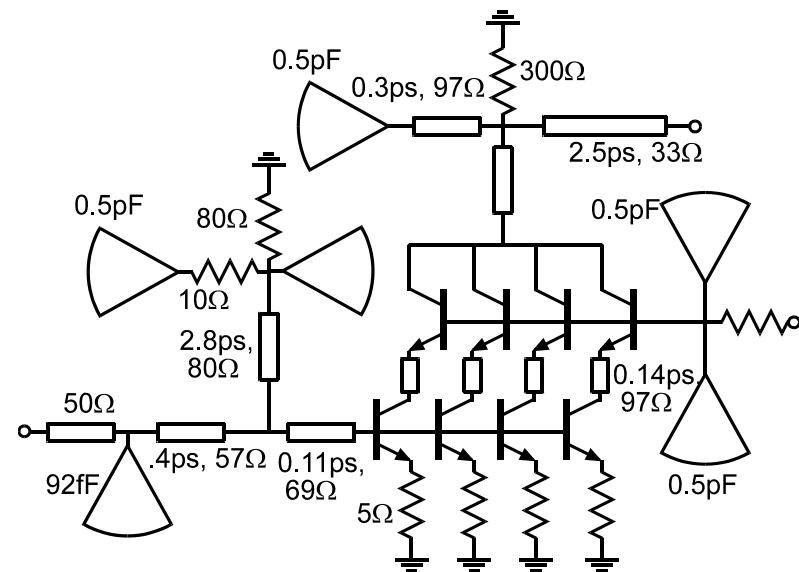
InGaAs-collector.

→ $V_{br} = 1.5 \text{ V}$ → **low power**

InP-collector.

→ $V_{br} \sim 5 \text{ V}$

→ **higher powers expected**





66 GHz HBT master-slave flip-flop

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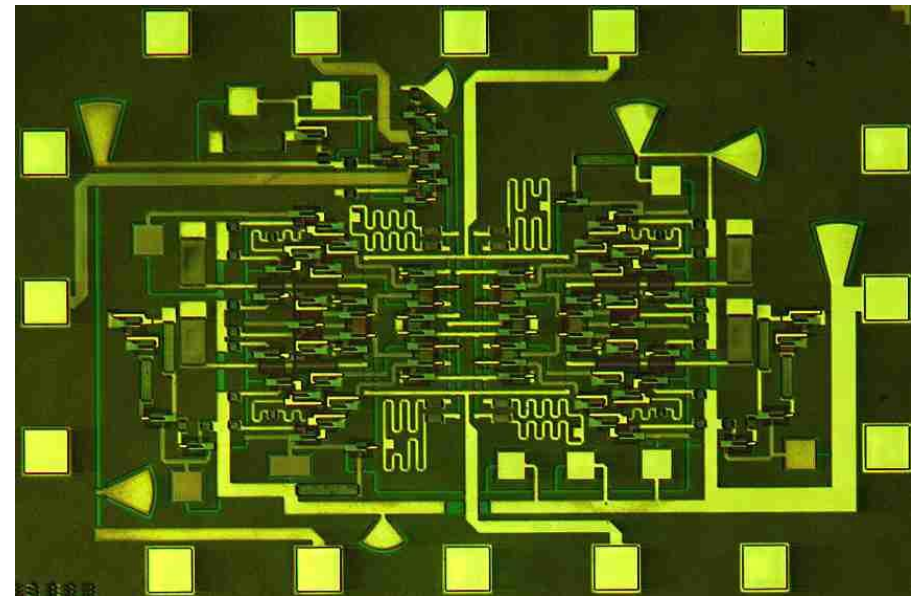
Michelle Lee

Objectives: 100 + GHz logic

Approach: transferred-substrate HBTs,
microwave / digital design

Simulations: 95 GHz clock rate in SPICE

Accomplishments:
operation to 66 GHz



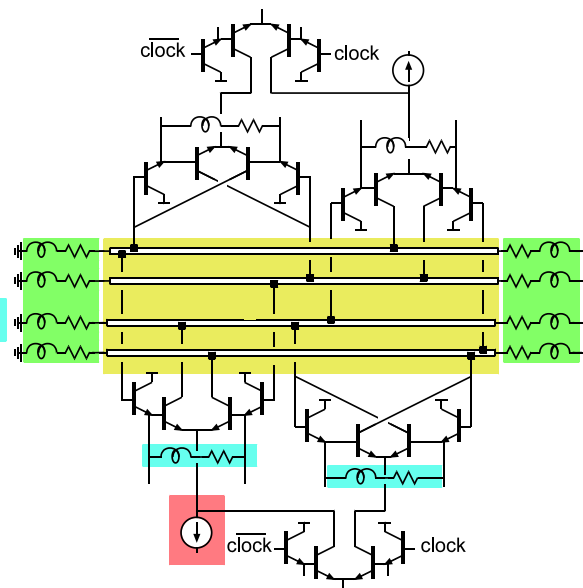
Design features:

transmission-line bus
short signal path

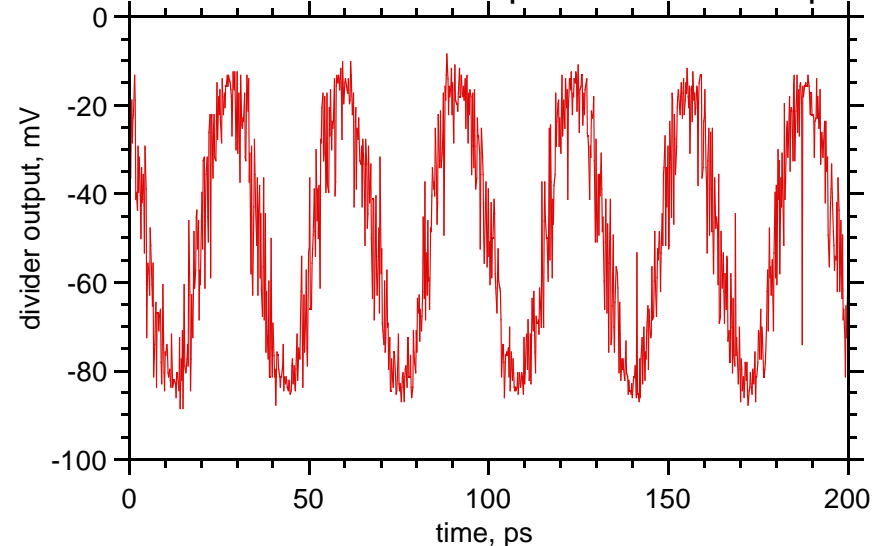
inductive load

emitter-follower damping

keep-alive bias currents



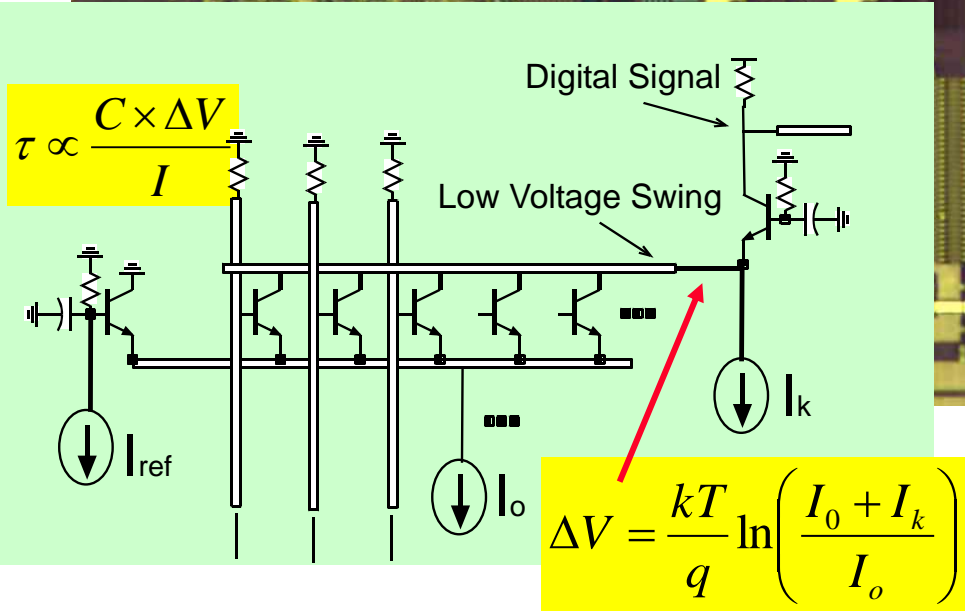
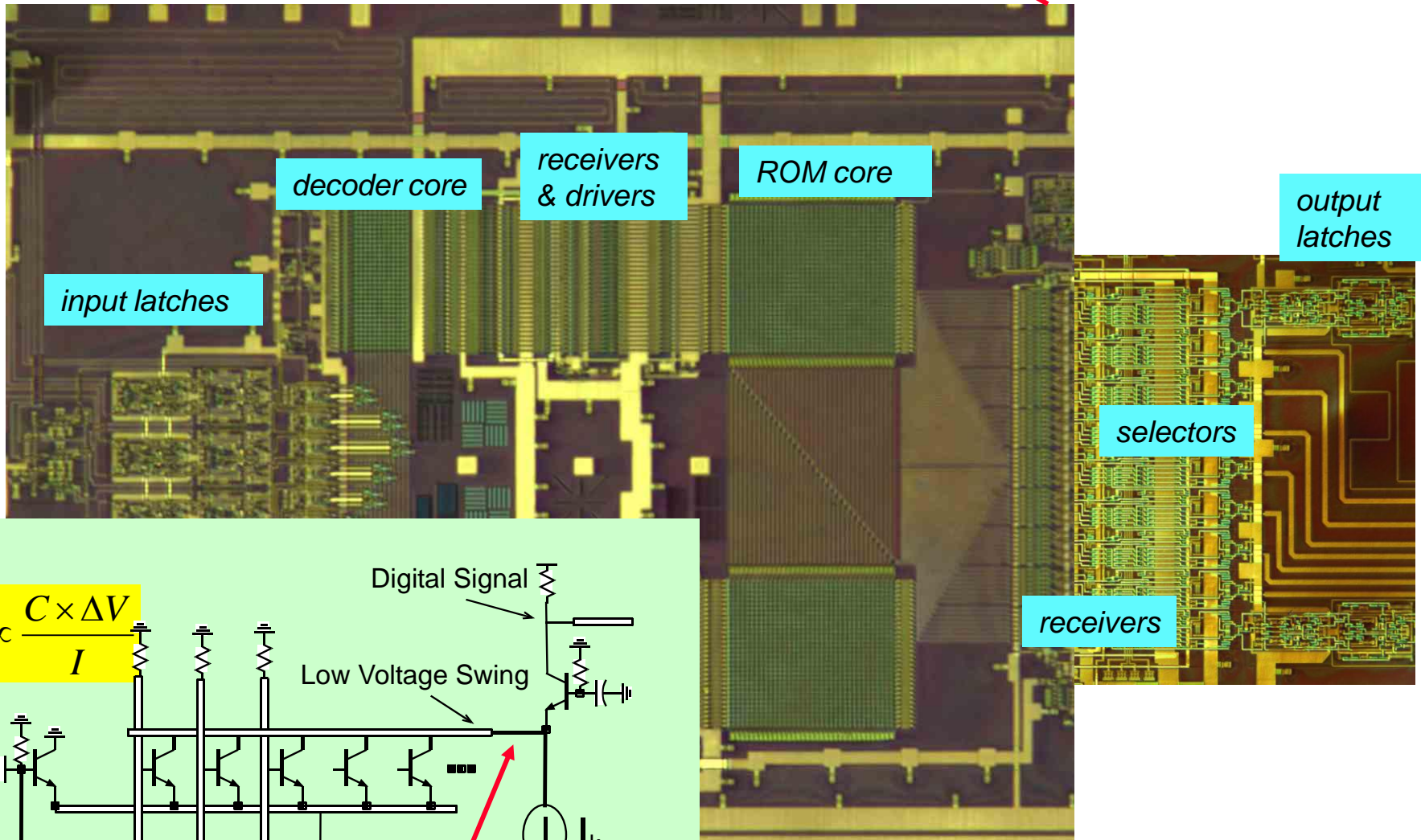
33.0 GHz static divider output at 66.0 GHz input





3500-HBT 20 GHz Sine ~~ROM~~ **WOM**

UCSB
Yoram Betser



(it is hard to build large ICs in a university cleanroom)

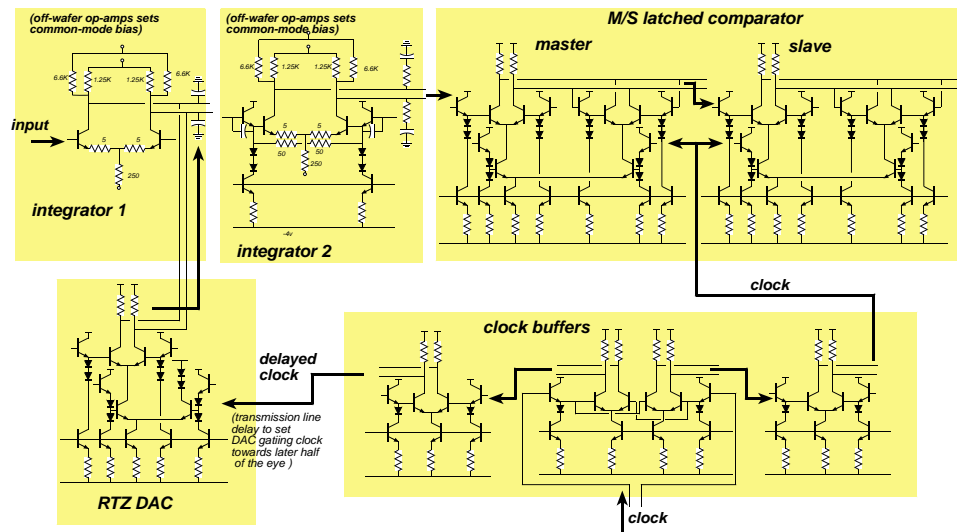
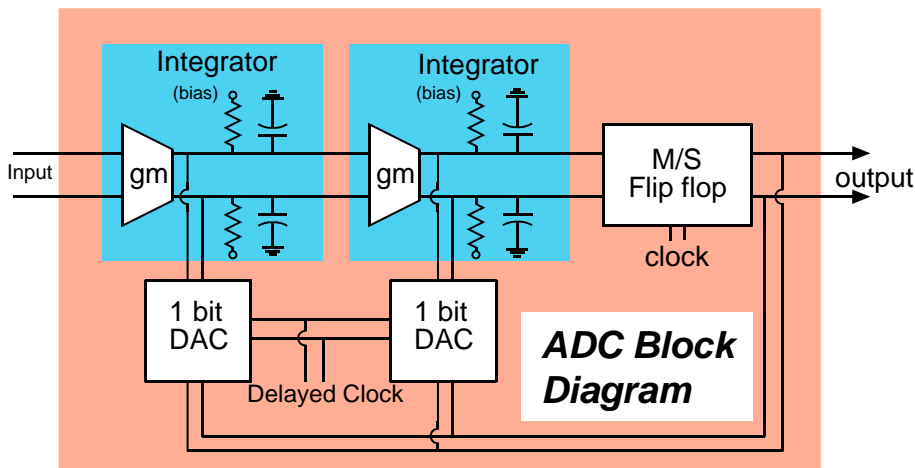
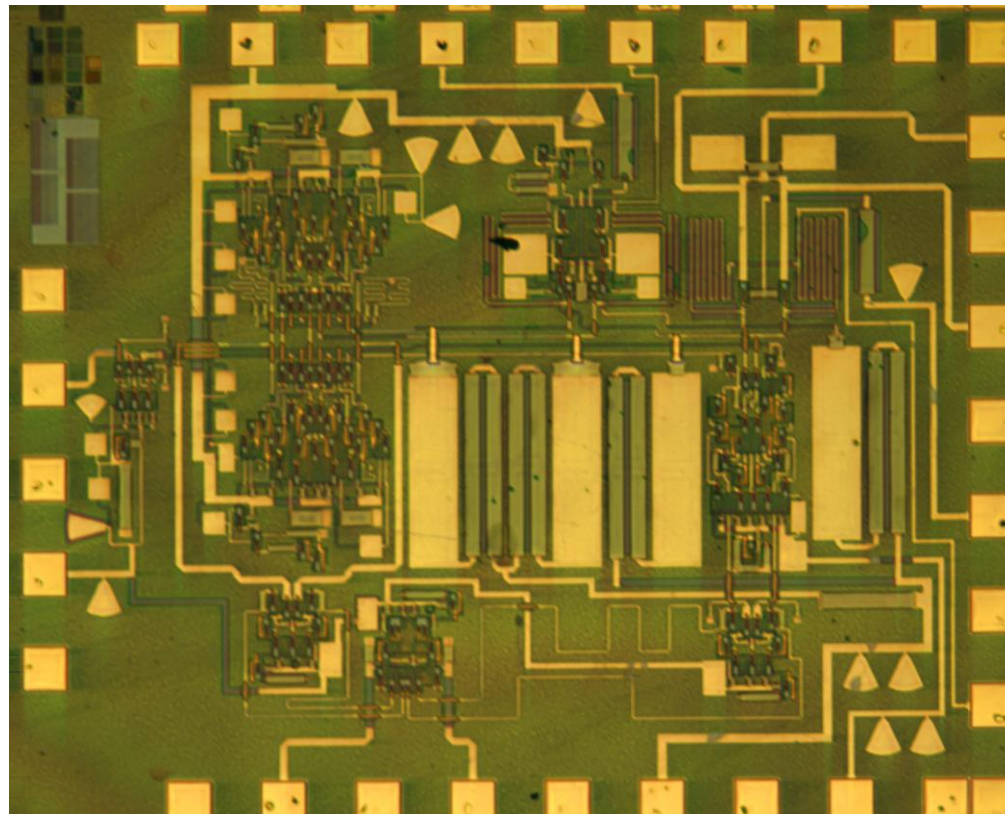
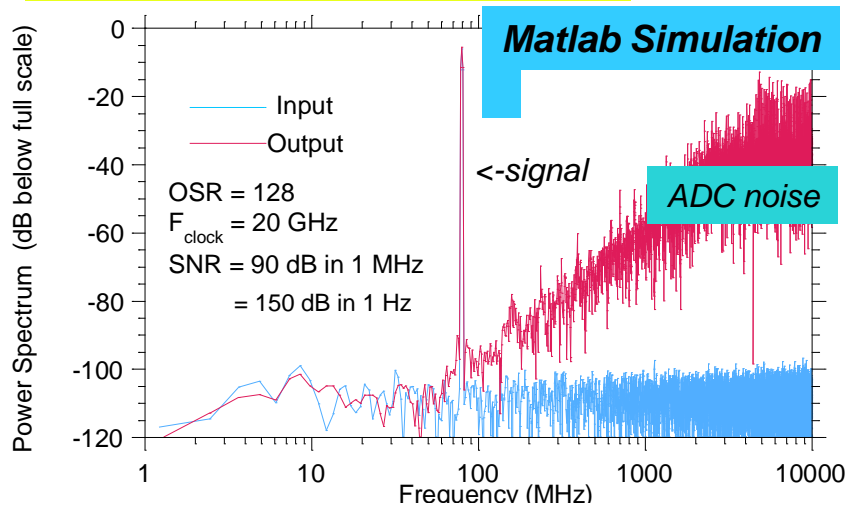


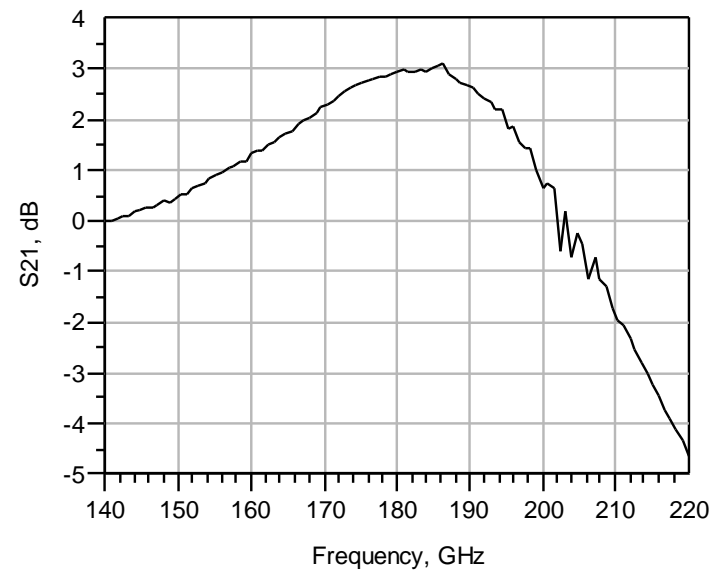
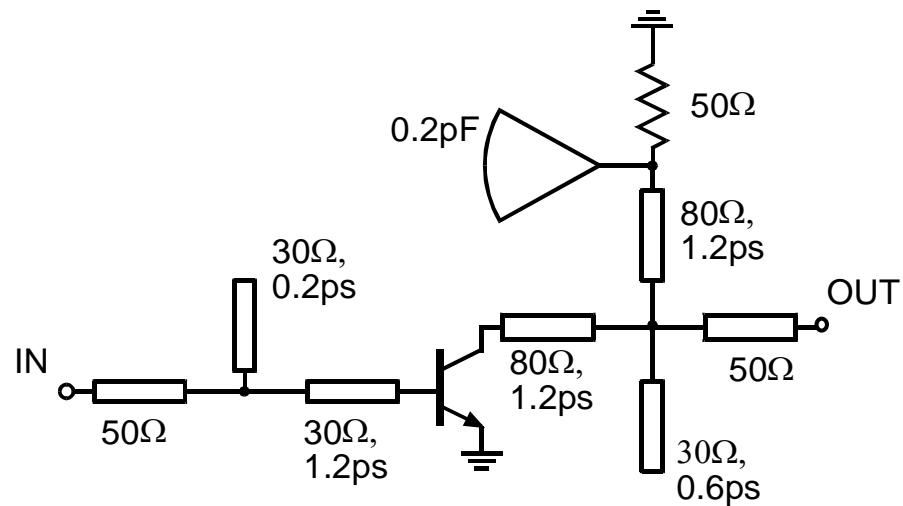
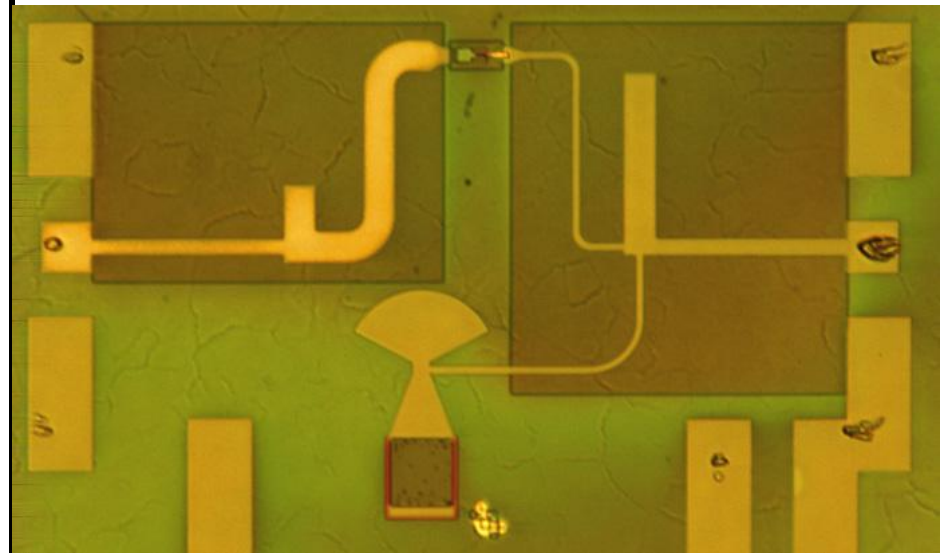
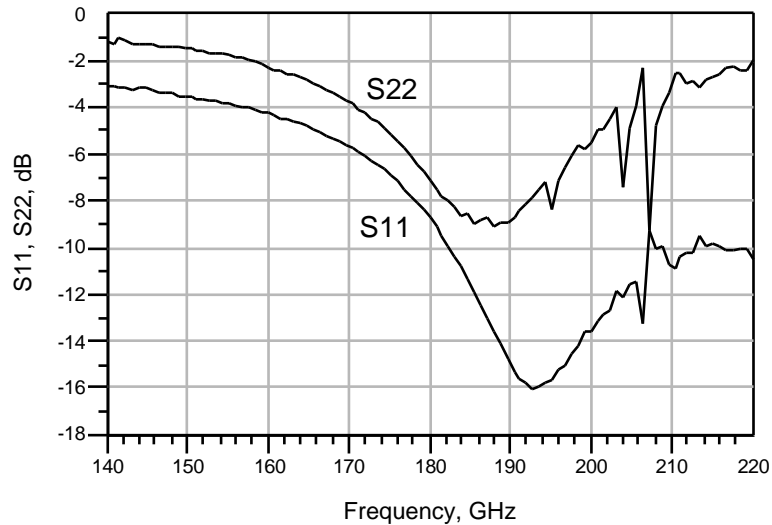
UCSB

Shrinivasan Jaganathan

Delta-Sigma ADC
18 GHz clock rate **150 HBTs**

6.2 ENOB for a 1 GHz signal
(2 GS/s equivalent Nyquist)







19 GHz 2-bit adder

UCSB

Thomas Mathew

